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# FSBB30CH60D

## Motion SPM® 3 Series

### Features

- UL Certified No. E209204 (UL1557)
- 600 V - 30 A 3-Phase IGBT Inverter with Integral Gate Drivers and Protection
- Low-Loss, Short-Circuit Rated IGBTs
- Very Low Thermal Resistance Using Al<sub>2</sub>O<sub>3</sub> DBC Substrate
- Built-In Bootstrap Diodes and Dedicated Vs Pins Simplify PCB Layout
- Separate Open-Emitter Pins from Low-Side IGBTs for Three-Phase Current Sensing
- Single-Grounded Power Supply
- LVIC Temperature-Sensing Built-In for Temperature Monitoring
- Isolation Rating: 2500 V<sub>rms</sub> / 1 min.

### General Description

FSBB30CH60D is an advanced Motion SPM® 3 module providing a fully-featured, high-performance inverter output stage for AC Induction, BLDC, and PMSM motors. These modules integrate optimized gate drive of the built-in IGBTs to minimize EMI and losses, while also providing multiple on-module protection features including under-voltage lockouts, over-current shutdown, thermal monitoring of drive IC, and fault reporting. The built-in, high-speed HVIC requires only a single supply voltage and translates the incoming logic-level gate inputs to the high-voltage, high-current drive signals required to properly drive the module's internal IGBTs. Separate negative IGBT terminals are available for each phase to support the widest variety of control algorithms.

### Applications

- Motion Control - Home Appliance / Industrial Motor

### Related Resources

- [AN-9085 - Motion SPM® 3 Ver.5 Series Users Guide](#)
- [AN-9086 - SPM 3 Package Mounting Guide](#)
- [AN-9087 - Motion SPM® 3 Ver.5 Series Thermal Performance Information](#)

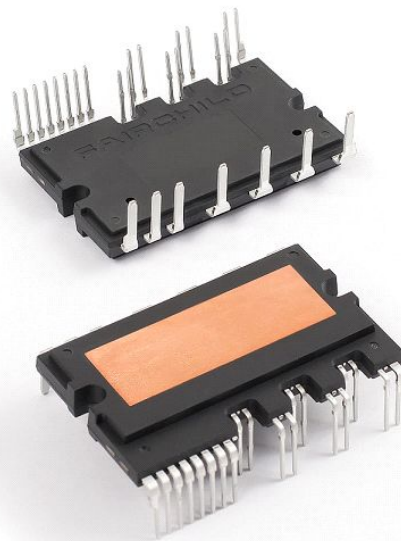


Figure 1. Package Overview

### Package Marking and Ordering Information

Device	Device Marking	Package	Packing Type	Quantity
FSBB30CH60D	FSBB30CH60D	SPMPA-027	Rail	10

### Integrated Power Functions

- 600 V - 30 A IGBT inverter for three-phase DC / AC power conversion (Please refer to Figure 3)

### Integrated Drive, Protection and System Control Functions

- For inverter high-side IGBTs: gate drive circuit, high-voltage isolated high-speed level shifting control circuit Under-Voltage Lock-Out Protection (UVLO)  
Note: Available bootstrap circuit example is given in Figures 5 and 15.
- For inverter low-side IGBTs: gate drive circuit, Short-Circuit Protection (SCP) control supply circuit Under-Voltage Lock-Out Protection (UVLO)
- Fault signaling: corresponding to UVLO (low-side supply) and SC faults
- Input interface: active-HIGH interface, works with 3.3 / 5 V logic, Schmitt-trigger input

### Pin Configuration

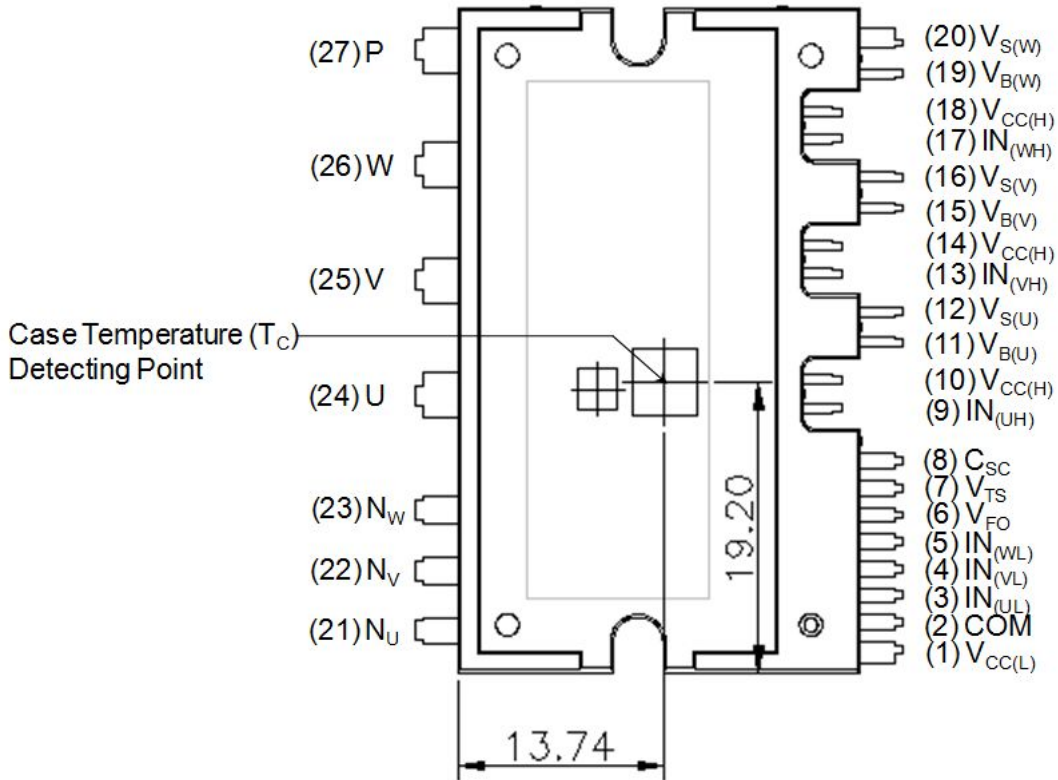


Figure 2. Top View

## Pin Descriptions

Pin Number	Pin Name	Pin Description
1	$V_{CC(L)}$	Low-Side Common Bias Voltage for IC and IGBTs Driving
2	COM	Common Supply Ground
3	$IN_{(UL)}$	Signal Input for Low-Side U-Phase
4	$IN_{(VL)}$	Signal Input for Low-Side V-Phase
5	$IN_{(WL)}$	Signal Input for Low-Side W-Phase
6	$V_{FO}$	Fault Output
7	$V_{TS}$	Output for LVIC Temperature Sensing Voltage Output
8	$C_{SC}$	Capacitor (Low-Pass Filter) for Short-Circuit Current Detection Input
9	$IN_{(UH)}$	Signal Input for High-Side U-Phase
10	$V_{CC(H)}$	High-Side Common Bias Voltage for IC and IGBTs Driving
11	$V_{B(U)}$	High-Side Bias Voltage for U-Phase IGBT Driving
12	$V_{S(U)}$	High-Side Bias Voltage Ground for U-Phase IGBT Driving
13	$IN_{(VH)}$	Signal Input for High-Side V-Phase
14	$V_{CC(H)}$	High-Side Common Bias Voltage for IC and IGBTs Driving
15	$V_{B(V)}$	High-Side Bias Voltage for V-Phase IGBT Driving
16	$V_{S(V)}$	High-Side Bias Voltage Ground for V Phase IGBT Driving
17	$IN_{(WH)}$	Signal Input for High-Side W-Phase
18	$V_{CC(H)}$	High-Side Common Bias Voltage for IC and IGBTs Driving
19	$V_{B(W)}$	High-Side Bias Voltage for W-Phase IGBT Driving
20	$V_{S(W)}$	High-Side Bias Voltage Ground for W-Phase IGBT Driving
21	$N_U$	Negative DC-Link Input for U-Phase
22	$N_V$	Negative DC-Link Input for V-Phase
23	$N_W$	Negative DC-Link Input for W-Phase
24	U	Output for U-Phase
25	V	Output for V-Phase
26	W	Output for W-Phase
27	P	Positive DC-Link Input



**Absolute Maximum Ratings** ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)

**Inverter Part**

Symbol	Parameter	Conditions	Rating	Unit
$V_{PN}$	Supply Voltage	Applied between P - $N_U$ , $N_V$ , $N_W$	450	V
$V_{PN(\text{Surge})}$	Supply Voltage (Surge)	Applied between P - $N_U$ , $N_V$ , $N_W$	500	V
$V_{CES}$	Collector - Emitter Voltage		600	V
$\pm I_C$	Each IGBT Collector Current	$T_C = 25^\circ\text{C}$ , $T_J \leq 150^\circ\text{C}$ (Note 4)	30	A
$\pm I_{CP}$	Each IGBT Collector Current (Peak)	$T_C = 25^\circ\text{C}$ , $T_J \leq 150^\circ\text{C}$ , Under 1 ms Pulse Width (Note 4)	60	A
$P_C$	Collector Dissipation	$T_C = 25^\circ\text{C}$ per One Chip (Note 4)	113	W
$T_J$	Operating Junction Temperature		-40 ~ 150	$^\circ\text{C}$

**Control Part**

Symbol	Parameter	Conditions	Rating	Unit
$V_{CC}$	Control Supply Voltage	Applied between $V_{CC(H)}$ , $V_{CC(L)}$ - COM	20	V
$V_{BS}$	High-Side Control Bias Voltage	Applied between $V_{B(U)} - V_{S(U)}$ , $V_{B(V)} - V_{S(V)}$ , $V_{B(W)} - V_{S(W)}$	20	V
$V_{IN}$	Input Signal Voltage	Applied between $IN_{(UH)}$ , $IN_{(VH)}$ , $IN_{(WH)}$ , $IN_{(UL)}$ , $IN_{(VL)}$ , $IN_{(WL)}$ - COM	-0.3 ~ $V_{CC}+0.3$	V
$V_{FO}$	Fault Output Supply Voltage	Applied between $V_{FO}$ - COM	-0.3 ~ $V_{CC}+0.3$	V
$I_{FO}$	Fault Output Current	Sink Current at $V_{FO}$ pin	2	mA
$V_{SC}$	Current Sensing Input Voltage	Applied between $C_{SC}$ - COM	-0.3 ~ $V_{CC}+0.3$	V

**Bootstrap Diode Part**

Symbol	Parameter	Conditions	Rating	Unit
$V_{RRM}$	Maximum Repetitive Reverse Voltage		600	V
$I_F$	Forward Current	$T_C = 25^\circ\text{C}$ , $T_J \leq 150^\circ\text{C}$ (Note 4)	0.5	A
$I_{FP}$	Forward Current (Peak)	$T_C = 25^\circ\text{C}$ , $T_J \leq 150^\circ\text{C}$ , Under 1 ms Pulse Width (Note 4)	2.0	A
$T_J$	Operating Junction Temperature		-40 ~ 150	$^\circ\text{C}$

**Total System**

Symbol	Parameter	Conditions	Rating	Unit
$V_{PN(\text{PROT})}$	Self Protection Supply Voltage Limit (Short Circuit Protection Capability)	$V_{CC} = V_{BS} = 13.5 \sim 16.5 \text{ V}$ , $T_J = 150^\circ\text{C}$ , Non-repetitive, $< 2 \mu\text{s}$	400	V
$T_C$	Module Case Operation Temperature	See Figure 2	-40 ~ 125	$^\circ\text{C}$
$T_{STG}$	Storage Temperature		-40 ~ 125	$^\circ\text{C}$
$V_{ISO}$	Isolation Voltage	60 Hz, Sinusoidal, AC 1 minute, Connection Pins to Heat Sink Plate	2500	$V_{\text{rms}}$

**Thermal Resistance**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{th(j-c)Q}$	Junction to Case Thermal Resistance (Note 5)	Inverter IGBT part (per 1 / 6 module)	-	-	1.10	$^\circ\text{C} / \text{W}$
$R_{th(j-c)F}$		Inverter FWD part (per 1 / 6 module)	-	-	2.10	$^\circ\text{C} / \text{W}$

**Note:**

- These values had been made an acquisition by the calculation considered to design factor.
- For the measurement point of case temperature ( $T_C$ ), please refer to Figure 2.

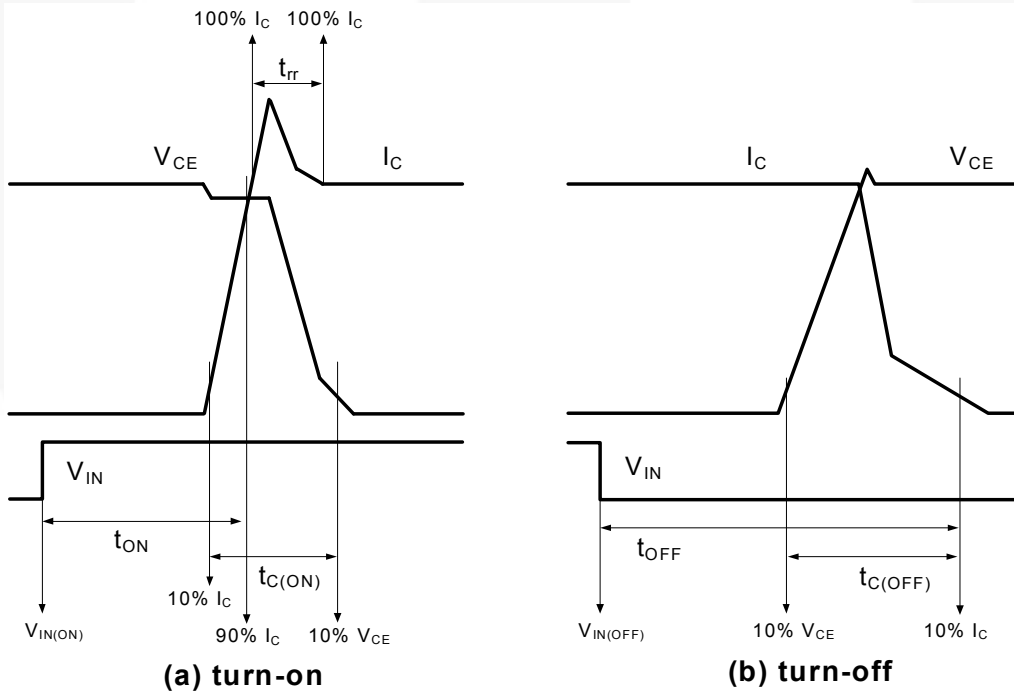
**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)

**Inverter Part**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	
$V_{CE(SAT)}$	Collector - Emitter Saturation Voltage	$V_{CC} = V_{BS} = 15\text{ V}$ $V_{IN} = 5\text{ V}$ $I_C = 30\text{ A}, T_J = 25^\circ\text{C}$	-	1.50	2.10	V	
$V_F$	FWDI Forward Voltage	$V_{IN} = 0\text{ V}$ $I_F = 30\text{ A}, T_J = 25^\circ\text{C}$	-	1.80	2.40	V	
HS	Switching Times	$V_{PN} = 300\text{ V}, V_{CC} = 15\text{ V}, I_C = 30\text{ A}$ $T_J = 25^\circ\text{C}$ $V_{IN} = 0\text{ V} \leftrightarrow 5\text{ V}$ , Inductive Load See Figure 5 (Note 6)	$t_{ON}$	0.50	0.90	1.40	$\mu\text{s}$
			$t_{C(ON)}$	-	0.25	0.55	$\mu\text{s}$
			$t_{OFF}$	-	0.90	1.40	$\mu\text{s}$
			$t_{C(OFF)}$	-	0.10	0.40	$\mu\text{s}$
			$t_{rr}$	-	0.10	-	$\mu\text{s}$
LS	Switching Times	$V_{PN} = 300\text{ V}, V_{CC} = 15\text{ V}, I_C = 30\text{ A}$ $T_J = 25^\circ\text{C}$ $V_{IN} = 0\text{ V} \leftrightarrow 5\text{ V}$ , Inductive Load See Figure 5 (Note 6)	$t_{ON}$	0.40	0.80	1.30	$\mu\text{s}$
			$t_{C(ON)}$	-	0.25	0.55	$\mu\text{s}$
			$t_{OFF}$	-	0.90	1.40	$\mu\text{s}$
			$t_{C(OFF)}$	-	0.15	0.45	$\mu\text{s}$
			$t_{rr}$	-	0.10	-	$\mu\text{s}$
$I_{CES}$	Collector - Emitter Leakage Current	$V_{CE} = V_{CES}$	-	-	5	mA	

**Note:**

6.  $t_{ON}$  and  $t_{OFF}$  include the propagation delay time of the internal drive IC.  $t_{C(ON)}$  and  $t_{C(OFF)}$  are the switching time of IGBT itself under the given gate driving condition internally. For the detailed information, please see Figure 4.



**Figure 4. Switching Time Definition**

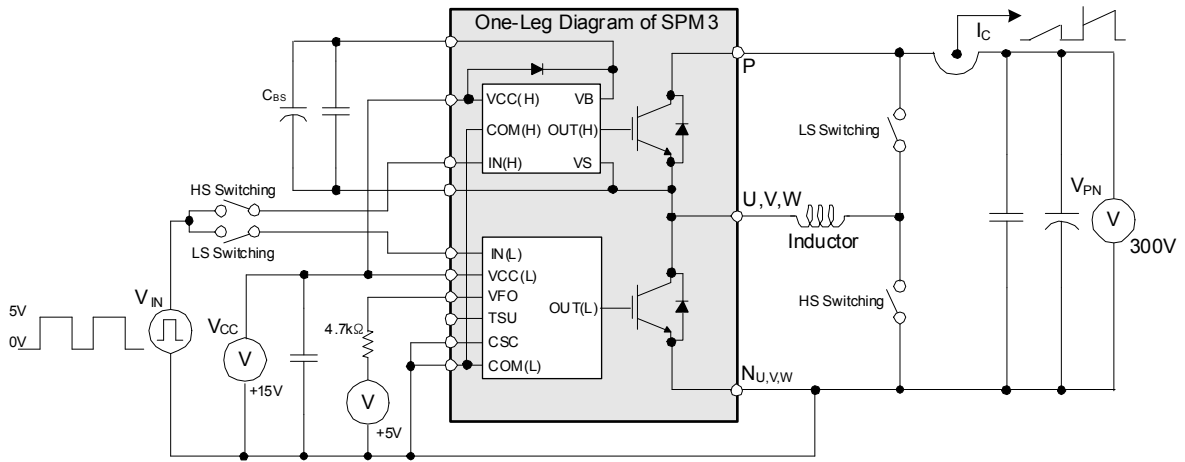


Figure 5. Example Circuit for Switching Test

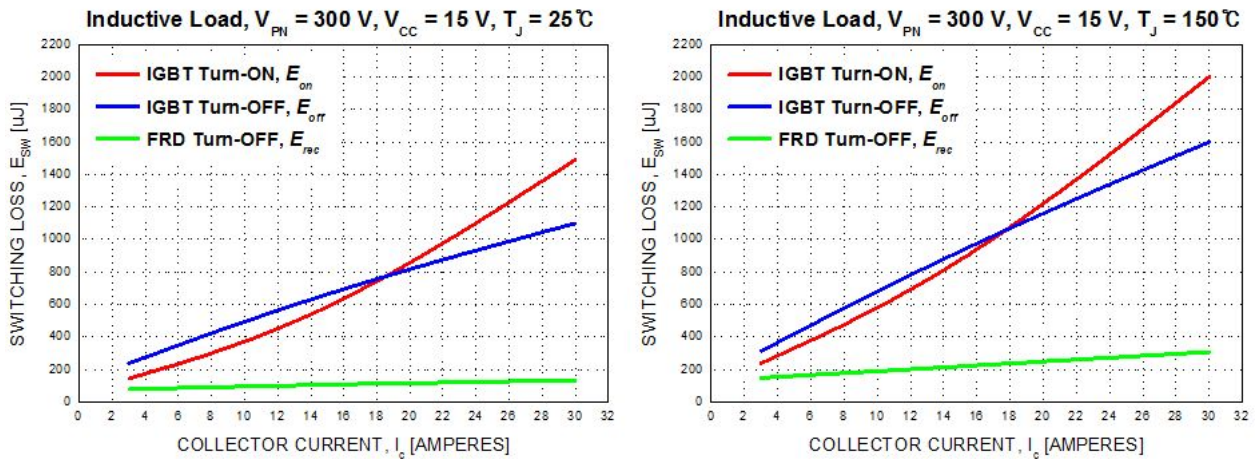


Figure 6. Switching Loss Characteristics

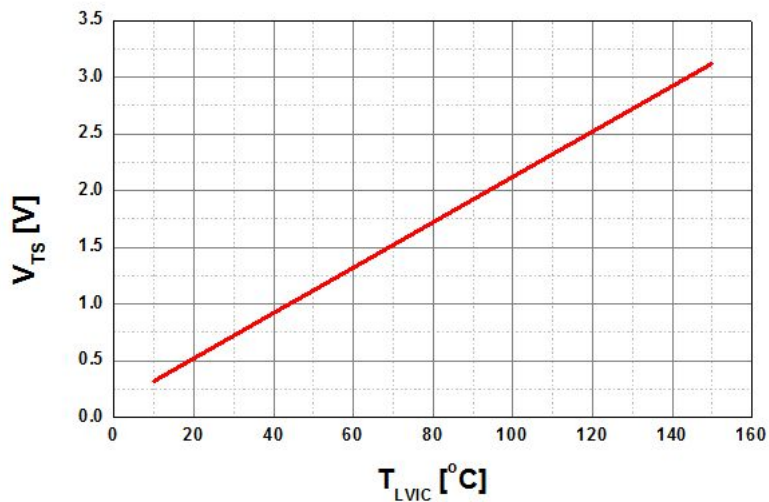


Figure 7. Temperature Profile of  $V_{TS}$  (Typical)



### Bootstrap Diode Part

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_F$	Forward Voltage	$I_F = 0.1 \text{ A}$ , $T_J = 25^\circ\text{C}$	-	2.5	-	V
$t_{rr}$	Reverse Recovery Time	$I_F = 0.1 \text{ A}$ , $dI_F / dt = 50 \text{ A} / \mu\text{s}$ , $T_J = 25^\circ\text{C}$	-	80	-	ns

### Control Part

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	
$I_{QCCH}$	Quiescent $V_{CC}$ Supply Current	$V_{CC(H)} = 15 \text{ V}$ , $I_{N(UH, VH, WH)} = 0 \text{ V}$	$V_{CC(H)} - \text{COM}$	-	-	0.50	mA
$I_{QCCL}$		$V_{CC(L)} = 15 \text{ V}$ , $I_{N(UL, VL, WL)} = 0 \text{ V}$	$V_{CC(L)} - \text{COM}$	-	-	6.00	mA
$I_{PCCH}$	Operating $V_{CC}$ Supply Current	$V_{CC(H)} = 15 \text{ V}$ , $f_{PWM} = 20 \text{ kHz}$ , duty = 50%, applied to one PWM signal input for High-Side	$V_{CC(H)} - \text{COM}$	-	-	0.50	mA
$I_{PCCL}$		$V_{CC(L)} = 15 \text{ V}$ , $f_{PWM} = 20 \text{ kHz}$ , duty = 50%, applied to one PWM signal input for Low-Side	$V_{CC(L)} - \text{COM}$	-	-	10.0	mA
$I_{QBS}$	Quiescent $V_{BS}$ Supply Current	$V_{BS} = 15 \text{ V}$ , $I_{N(UH, VH, WH)} = 0 \text{ V}$	$V_{B(U)} - V_{S(U)}$ , $V_{B(V)} - V_{S(V)}$ , $V_{B(W)} - V_{S(W)}$	-	-	0.30	mA
$I_{PBS}$	Operating $V_{BS}$ Supply Current	$V_{CC} = V_{BS} = 15 \text{ V}$ , $f_{PWM} = 20 \text{ kHz}$ , duty = 50%, applied to one PWM signal input for High-Side	$V_{B(U)} - V_{S(U)}$ , $V_{B(V)} - V_{S(V)}$ , $V_{B(W)} - V_{S(W)}$	-	-	4.50	mA
$V_{FOH}$	Fault Output Voltage	$V_{CC} = 15 \text{ V}$ , $V_{SC} = 0 \text{ V}$ , $V_{FO}$ Circuit: 4.7 k $\Omega$ to 5 V Pull-up		4.5	-	-	V
$V_{FOL}$		$V_{CC} = 15 \text{ V}$ , $V_{SC} = 1 \text{ V}$ , $V_{FO}$ Circuit: 4.7 k $\Omega$ to 5 V Pull-up		-	-	0.5	V
$V_{SC(ref)}$	Short Circuit Trip Level	$V_{CC} = 15 \text{ V}$ (Note 7)	$C_{SC} - \text{COM}_{(L)}$	0.45	0.50	0.55	V
$UV_{CCD}$	Supply Circuit Under-Voltage Protection	Detection Level		9.8	-	13.3	V
$UV_{CCR}$		Reset Level		10.3	-	13.8	V
$UV_{BSD}$		Detection Level		9.0	-	12.5	V
$UV_{BSR}$		Reset Level		9.5	-	13.0	V
$t_{FOD}$	Fault-Out Pulse Width			50	-	-	$\mu\text{s}$
$V_{TS}$	LVIC Temperature Sensing Voltage Output	$V_{CC(L)} = 15 \text{ V}$ , $T_{LVIC} = 25^\circ\text{C}$ (Note 8) <i>See Figure 7</i>		540	640	740	mV
$V_{IN(ON)}$	ON Threshold Voltage	Applied between $I_{N(UH, VH, WH)} - \text{COM}$ , $I_{N(UL, VL, WL)} - \text{COM}$		-	-	2.6	V
$V_{IN(OFF)}$	OFF Threshold Voltage			0.8	-	-	V

**Note:**

7. Short-circuit current protection is functioning only at the low-sides.

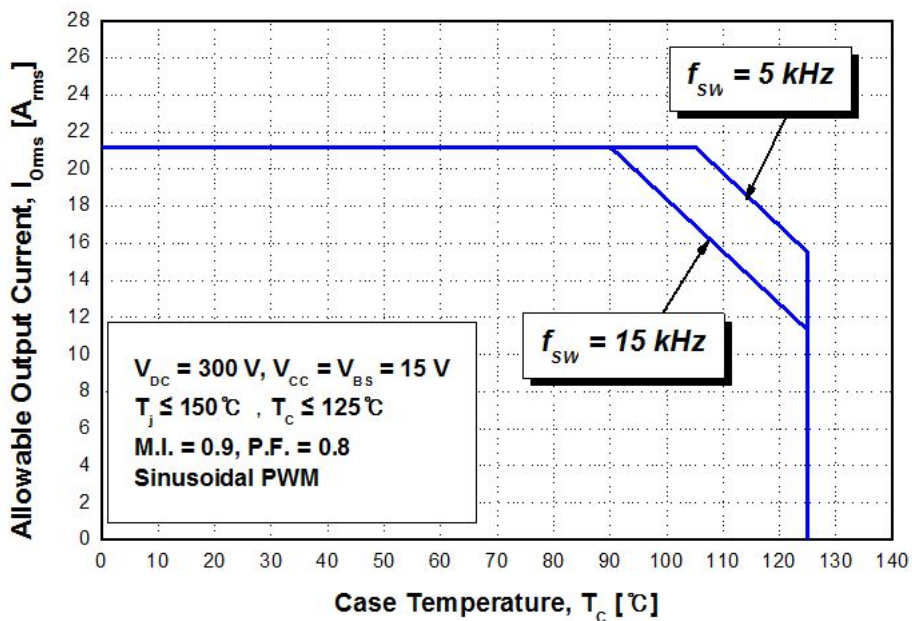
8.  $T_{LVIC}$  is the temperature of LVIC itself.  $V_{TS}$  is only for sensing temperature of LVIC and can not shutdown IGBTs automatically.

### Recommended Operating Conditions

Symbol	Parameter	Conditions	Value			Unit
			Min.	Typ.	Max.	
$V_{PN}$	Supply Voltage	Applied between P - $N_U, N_V, N_W$	-	300	400	V
$V_{CC}$	Control Supply Voltage	Applied between $V_{CC(UH, VH, WH)} - COM, V_{CC(L)} - COM$	14.0	15	16.5	V
$V_{BS}$	High-Side Bias Voltage	Applied between $V_{B(U)} - V_{S(U)}, V_{B(V)} - V_{S(V)}, V_{B(W)} - V_{S(W)}$	13.0	15	18.5	V
$dV_{CC}/dt, dV_{BS}/dt$	Control Supply Variation		-1	-	1	V/ $\mu$ s
$t_{dead}$	Blanking Time for Preventing Arm - Short	For Each Input Signal	1.0	-	-	$\mu$ s
$f_{PWM}$	PWM Input Signal	$-40^\circ\text{C} \leq T_C \leq 125^\circ\text{C}, -40^\circ\text{C} \leq T_J \leq 150^\circ\text{C}$	-	-	20	kHz
$V_{SEN}$	Voltage for Current Sensing	Applied between $N_U, N_V, N_W - COM$ (Including Surge Voltage)	-5	-	5	V
$PW_{IN(ON)}$	Minimum Input Pulse Width	$V_{CC} = V_{BS} = 15\text{ V}, I_C \leq 60\text{ A}$ , Wiring Inductance between $N_U, v, w$ and DC Link N < 10nH (Note 9)	2.0	-	-	$\mu$ s
$PW_{IN(OFF)}$			2.0	-	-	
$T_J$	Junction Temperature		-40	-	150	$^\circ\text{C}$

**Note:**

9. This product might not make response if input pulse width is less than the recommended value.



**Note:**

10. This allowable output current value is the reference data for the safe operation of this product. This may be different from the actual application and operating condition.

### Mechanical Characteristics and Ratings

Parameter	Conditions	Limits			Unit	
		Min.	Typ.	Max.		
Device Flatness	See Figure 9	0	-	+150	μm	
Mounting Torque	Mounting Screw: M3	Recommended 0.7 N • m	0.6	0.7	0.8	N • m
	See Figure 10	Recommended 7.1 kg • cm	6.2	7.1	8.1	kg • cm
Terminal Pulling Strength	Load 19.6 N	10	-	-	s	
Terminal Bending Strength	Load 9.8 N, 90 deg. bend	2	-	-	times	
Weight		-	15	-	g	

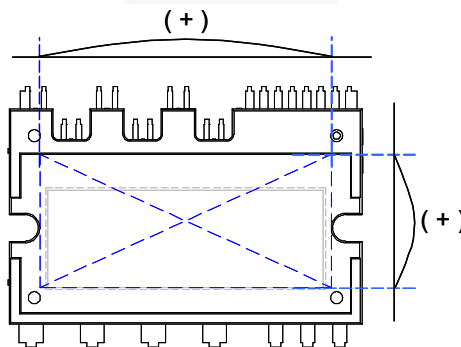


Figure 9. Flatness Measurement Position

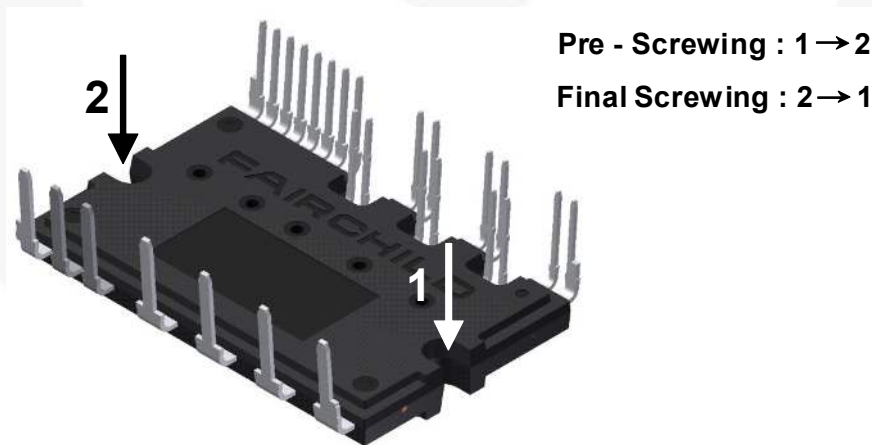
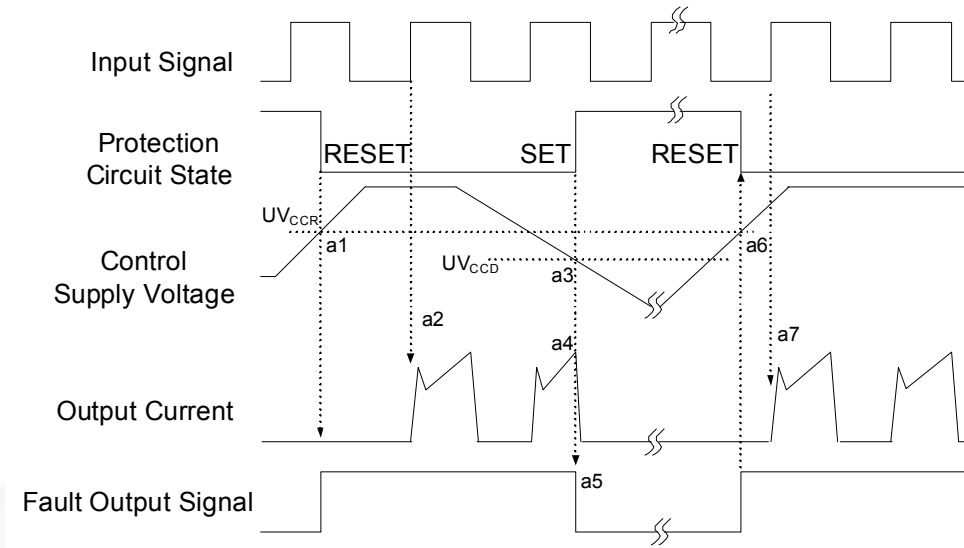


Figure 10. Mounting Screws Torque Order

**Note:**

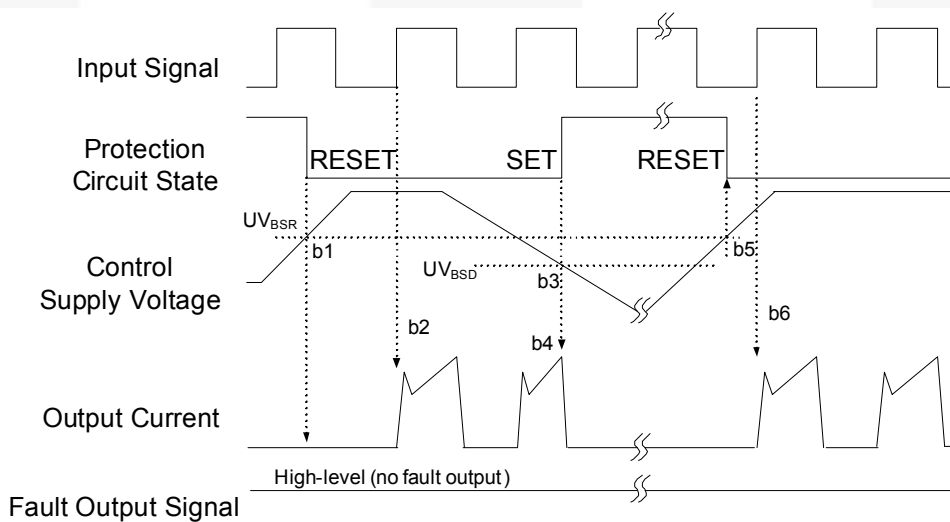
- 11. Do not make over torque when mounting screws. Much mounting torque may cause DBC cracks, as well as bolts and Al heat-sink destruction.
- 12. Avoid one-sided tightening stress. Figure 10 shows the recommended torque order for mounting screws. Uneven mounting can cause the DBC substrate of package to be damaged. The pre-screwing torque is set to 20 ~ 30% of maximum torque rating.

### Time Charts of SPMs Protective Function



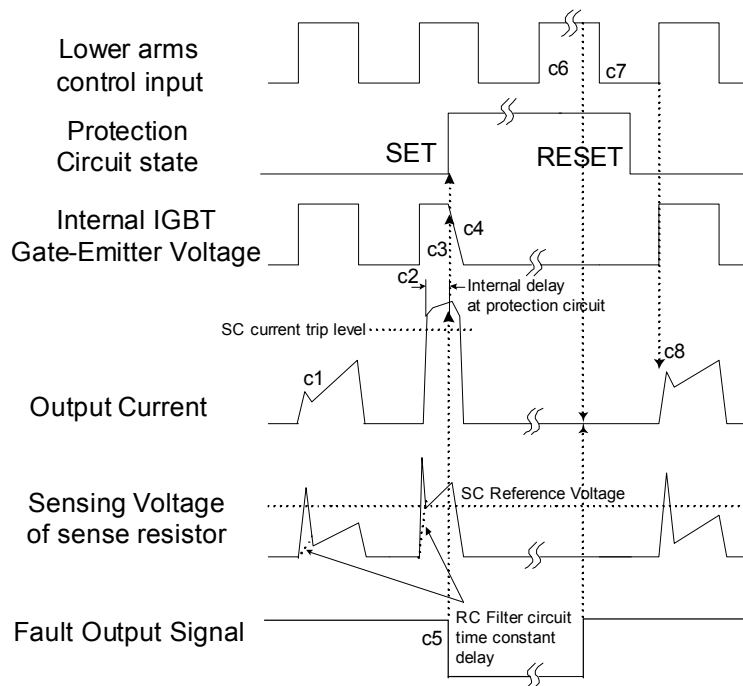
**Figure 11. Under-Voltage Protection (Low-Side)**

- a1 : Control supply voltage rises: After the voltage rises  $UV_{CCR}$ , the circuits start to operate when next input is applied.
- a2 : Normal operation: IGBT ON and carrying current.
- a3 : Under voltage detection ( $UV_{CCD}$ ).
- a4 : IGBT OFF in spite of control input condition.
- a5 : Fault output operation starts with a fixed pulse width.
- a6 : Under voltage reset ( $UV_{CCR}$ ).
- a7 : Normal operation: IGBT ON and carrying current by triggering next signal from LOW to HIGH.



**Figure 12. Under-Voltage Protection (High-Side)**

- b1 : Control supply voltage rises: After the voltage reaches  $UV_{BSR}$ , the circuits start to operate when next input is applied.
- b2 : Normal operation: IGBT ON and carrying current.
- b3 : Under voltage detection ( $UV_{BSD}$ ).
- b4 : IGBT OFF in spite of control input condition, but there is no fault output signal.
- b5 : Under voltage reset ( $UV_{BSR}$ ).
- b6 : Normal operation: IGBT ON and carrying current by triggering next signal from LOW to HIGH.

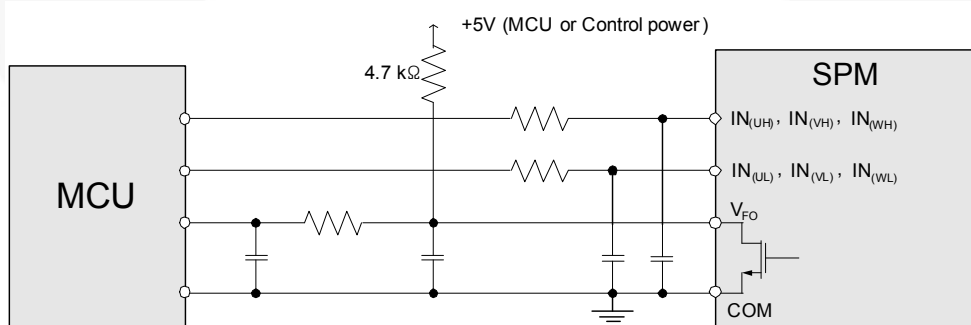


**Figure 13. Short-Circuit Current Protection (Low-Side Operation only)**

(with the external sense resistance and RC filter connection)

- c1 : Normal operation: IGBT ON and carrying current.
- c2 : Short circuit current detection (SC trigger).
- c3 : All low-side IGBT's gate are hard interrupted.
- c4 : All low-side IGBTs turn OFF.
- c5 : Fault output operation starts with a fixed pulse width.
- c6 : Input HIGH: IGBT ON state, but during the active period of fault output the IGBT doesn't turn ON.
- c7 : Fault output operation finishes, but IGBT doesn't turn on until triggering next signal from LOW to HIGH.
- c8 : Normal operation: IGBT ON and carrying current.

### Input/Output Interface Circuit



**Figure 14. Recommended CPU I/O Interface Circuit**

**Note:**

13. RC coupling at each input might change depending on the PWM control scheme used in the application and the wiring impedance of the application's printed circuit board. The input signal section of the Motion SPM 3 product integrates 5 kΩ (typ.) pull-down resistor. Therefore, when using an external filtering resistor, please pay attention to the signal voltage drop at input terminal.

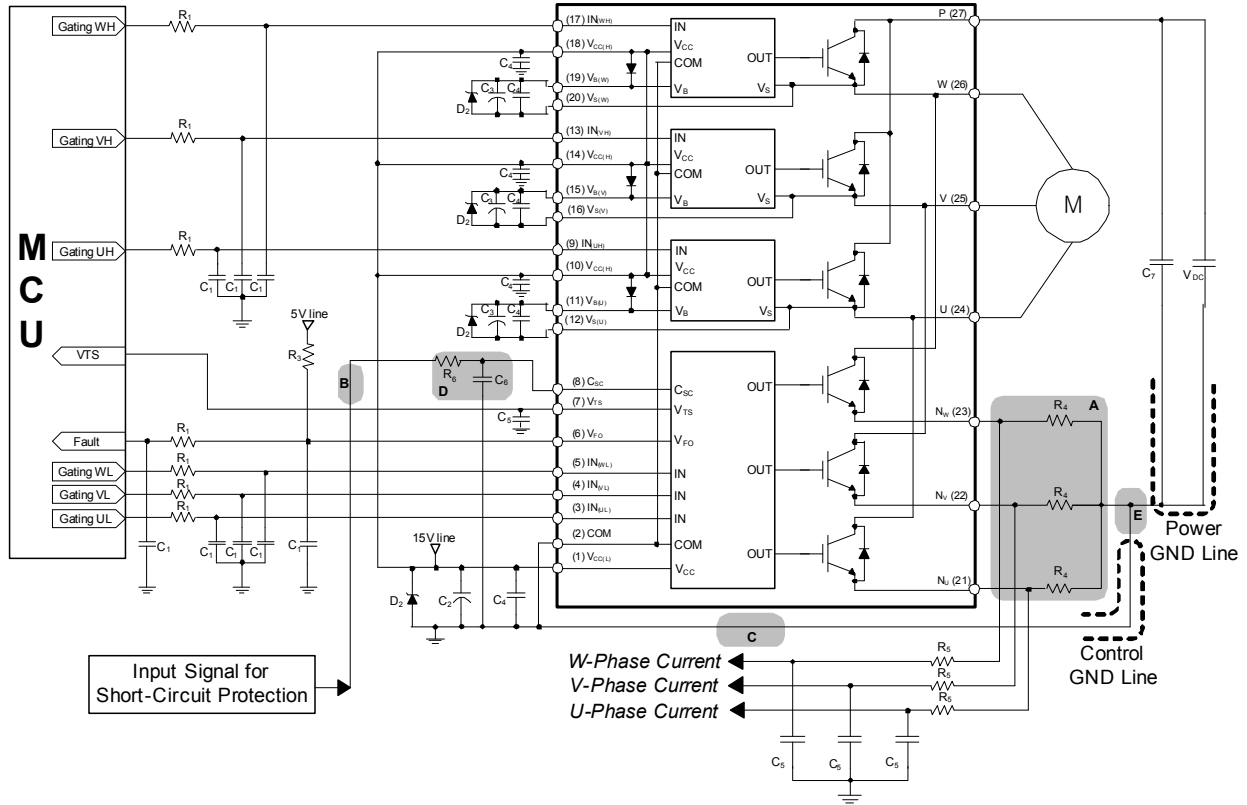
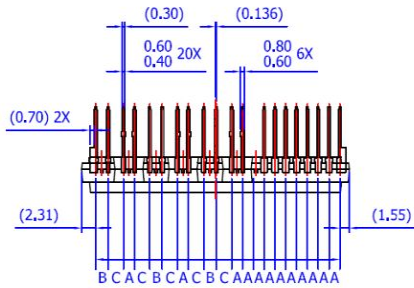


Figure 15. Typical Application Circuit

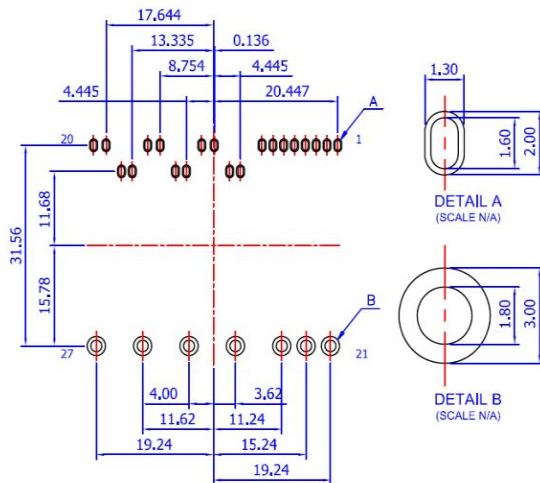
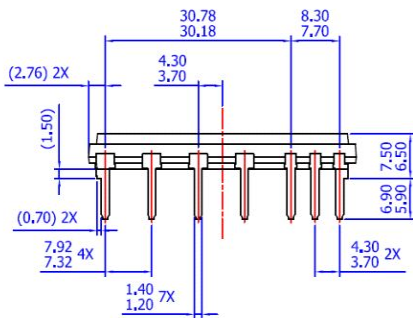
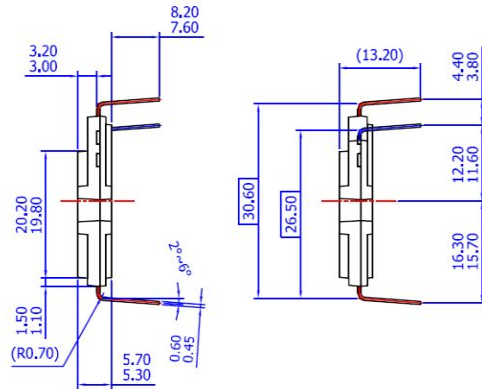
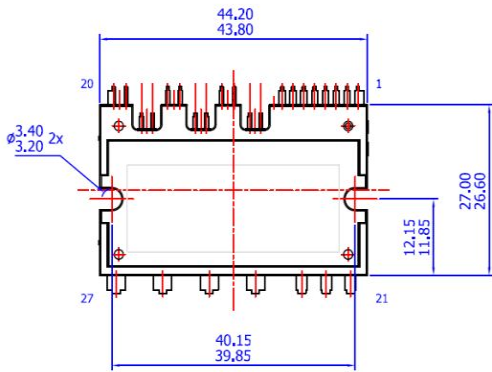
Note:

14. To avoid malfunction, the wiring of each input should be as short as possible. (less than 2 - 3 cm)
15.  $V_{FO}$  output is open-drain type. This signal line should be pulled up to the positive side of the MCU or control power supply with a resistor that makes  $I_{FO}$  up to 2 mA. Please refer to Figure 14.
16. Input signal is active-HIGH type. There is a 5 k $\Omega$  resistor inside the IC to pull-down each input signal line to GND. RC coupling circuits should be adopted for the prevention of input signal oscillation.  $R_1C_1$  time constant should be selected in the range 50 ~ 150 ns. (Recommended  $R_1 = 100 \Omega$ ,  $C_1 = 1$  nF)
17. Each wiring pattern inductance of A point should be minimized (Recommend less than 10nH). Use the shunt resistor  $R_4$  of surface mounted (SMD) type to reduce wiring inductance. To prevent malfunction, wiring of point E should be connected to the terminal of the shunt resistor  $R_4$  as close as possible.
18. To prevent errors of the protection function, the wiring of B, C, and D point should be as short as possible.
19. In the short-circuit protection circuit, please select the  $R_6C_6$  time constant in the range 1.5 ~ 2  $\mu$ s. Do enough evaluation on the real system because short-circuit protection time may vary wiring pattern layout and value of the  $R_6C_6$  time constant.
20. Each capacitor should be mounted as close to the pins of the Motion SPM® 3 product as possible.
21. To prevent surge destruction, the wiring between the smoothing capacitor  $C_7$  and the P & GND pins should be as short as possible. The use of a high-frequency non-inductive capacitor of around 0.1 ~ 0.22  $\mu$ F between the P & GND pins is recommended.
22. Relays are used at almost every systems of electrical equipments at industrial application. In these cases, there should be sufficient distance between the CPU and the relays.
23. The zener diode or transient voltage suppressor should be adopted for the protection of ICs from the surge destruction between each pair of control supply terminals (Recommended zener diode is 22 V / 1 W, which has the lower zener impedance characteristic than about 15 $\Omega$ ).
24.  $C_2$  of around 7 times larger than bootstrap capacitor  $C_3$  is recommended.
25. Please choose the electrolytic capacitor with good temperature characteristic in  $C_3$ . Also, choose 0.1 ~ 0.2  $\mu$ F R-category ceramic capacitors with good temperature and frequency characteristics in  $C_4$ .

Detailed Package Outline Drawings (FSBB30CH60D)



LEAD PITCH (TOLERANCE : ±0.30)  
 A : 1.778  
 B : 2.050  
 C : 2.531



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	MicroPak2™	STEALTH™	Ultra FRFET™
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